

IN THE CLAIMS:

For the Examiner's convenience, all pending claims are presented below with changes shown in accordance with the mandatory amendment format.

1. (Currently Amended) An apparatus, comprising:

an absorber section of a heat pipe attached to a first end of a base of the heat pipe
[[, the absorber section]] to remove heat from a heat spreader, wherein the absorber
section having a size of at least a surface area of the heat spreader; and

a dissipater section of [[a]] the heat pipe attached to a second end of [[a]] the base
of the heat pipe, wherein a width of the dissipater section is greater than a width of the
base of the heat pipe, and the dissipater section having a size of at least a surface area of
the ~~heat spreader~~ absorber section.

2.-5. (Cancelled)

6. (Previously Presented) The apparatus of Claim 5, further comprising:

a plurality of fins formed of the second end of the base, the plurality of fins
attached to a bottom surface of the heat dissipater, the fins having a length approximately
equal to the width of the base.

7.-12. (Cancelled)

13. (Previously Presented) A computer system, comprising:

a central processing unit (CPU);

a heat absorber attached to a first end of a base of a heat pipe and having a size of
at least a surface area of a heat spreader; and

a heat dissipater attached to a second end of the base of the heat pipe, wherein a width of the heat dissipater is greater than a width of the base of the heat pipe, and the heat dissipater having a size of at least a surface area of the heat absorber ~~a heat spreader~~.

14.-16. (Cancelled)

17. (Previously Presented) The computer system of Claim 16, further comprising:
a plurality of fins formed on the second end of the base, the plurality of fins attached to a bottom surface of the heat dissipater, the plurality of fins having a length approximately equal to the width of the base.

18. (Cancelled)

19. (New) The apparatus of claim 1, wherein the absorber section and the base of the heat pipe are formed of a thermally conductive material selected from the group including copper, a copper alloy, and aluminum.

20. (New) The apparatus of claim 1, wherein the absorber section is attached to the heat spreader by a thermal interface material.

21. (New) The apparatus of claim 6, wherein the plurality of fins are formed of a thermally conductive material selected from the group including copper, a copper alloy, and aluminum.

22. (New) The apparatus of claim 1, wherein the absorber section and the dissipater section are the same size.

23. (New) The system of claim 13, wherein the heat absorber and the base of the heat pipe are formed of a thermally conductive material selected from the group including copper, a copper alloy, and aluminum.
24. (New) The system of claim 13, wherein the heat absorber is attached to the heat spreader by a thermal interface material.
25. (New) The system of claim 13, wherein the heat absorber removes heat from the heat spreader.
26. (New) The system of claim 17, further comprising a fan to direct air across at least one of the plurality of fins and the base of the heat pipe to dissipate heat produced by the CPU.
27. (New) The system of claim 17, wherein the plurality of fins are formed of a thermally conductive material selected from the group including copper, a copper alloy, and aluminum.